

Solid State Devices, Inc.

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Designer's Data Sheet

Part Number/Ordering Information ^{1/}

L Screening 2/ = Not Screened TX = TX Level TXV = TXV S = S Level

Package Type

= Axial Leaded
SM = Surface Mount Round Tab
SMS = Surface Mount Square Tab

Family/Voltage

1502 = 150 V 2002 = 200 V

SPD1502 thru SPD2002 Series

2 AMP 150 - 200 VOLTS SCHOTTKY RECTIFIER

Features:

- PIV to 200 Volts
- Extremely Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Surge Capacity
- Possible Replacement for 1N5802 1N5806 Series
- Hermetically Sealed
- For low voltage versions, see data sheet RS0006
- TX, TXV, and Space Level Screening Available^{2/}
- Category III metallurgical bond per MIL-PRF-19500 appendix A

Maximum Ratings		Symbol	Value	Units
Reverse Voltage	SPD1502 SPD2002	$egin{array}{c} oldsymbol{V_{RRM}} \ oldsymbol{V_{R}} \end{array}$	150 200	Volts
Average Rectified Forward Current (Resistive Load, 60Hz, Sine Wave, T _L or T _E = 55°C)		Io	2	Amps
Peak Surge Current (8.3 ms Pulse, allow junction to reach equilibrium between pulses, TA = 25°C)		I _{FSM}	40	Amps
Operating and Storage Temperature Range		T _{OP} & T _{STG}	-55 to +150	°C
Maximum Thermal Resistance Junction to Lead, L = .25" (Axial Lead) Junction to End Tab (Surface Mount)		R _{OJL} R _{OJE}	70 50	°C/W

NOTES:

 $\underline{\textbf{1}}{/}$ For ordering information, price, and availability-Contact factory.

2/ Screening based on MIL-PRF-19500. Screening flows available on request.

Axial Lead

Surface Mount Round Tab

Surface Mount Square Tab



NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: SH0077B

DOC



SPD1502 thru SPD2002 Series

 C_J

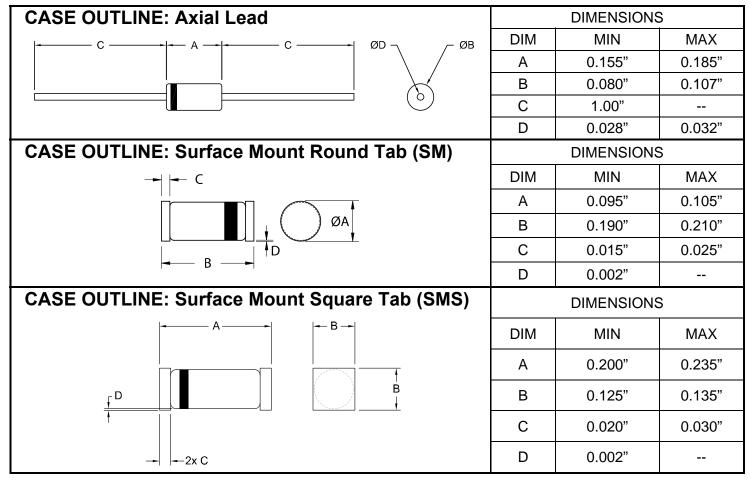
40

pF

Electrical Characteristic		Symbol	Min	Max	Units
Instantaneous Forward Voltage Drop (T _J = 25°C, 300 - 500 µsec pulse)	$I_F = 0.5A$ $I_F = 1A$ $I_F = 2A$	V _{F1} V _{F2} V _{F3}	 	0.78 0.85 0.95	Volts
Instantaneous Forward Voltage Drop (I _F = 1A, 300 - 500 µsec pulse)	$T_A = -55^{\circ}C$ $T_A = 100^{\circ}C$	$oldsymbol{V_{F4}}{oldsymbol{V_{F5}}}$		1.10 0.78	Volts
Reverse Leakage Current (V _R = Rated V _R , T _A = 25°C, 300 μsec min pulse)		I _{R1}		100	μΑ
Reverse Leakage Current ($V_R = Rated V_R$, $T_A = 100^{\circ}C$, 300 µsec min pulse)		I _{R2}		2	mA
Junction Capacitance	_	•		40	n.E

Consult manufacturing for operating curves

 $(V_R=10 \text{ Vdc}, T_A=25^{\circ}\text{C}, f=1\text{MHz})$



Dimensions prior to solder dip